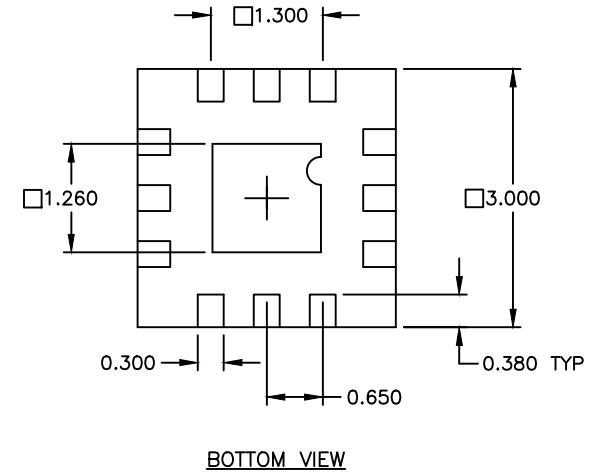
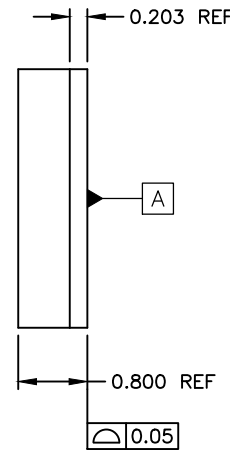
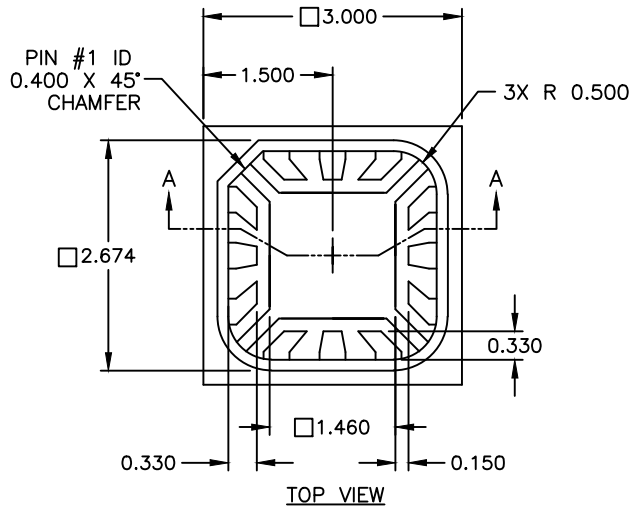


2

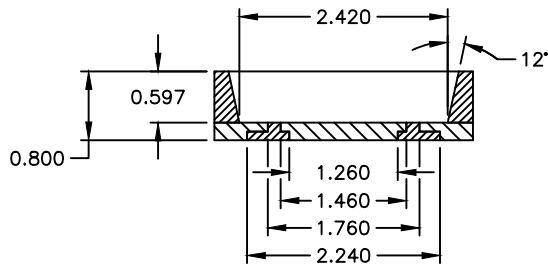
1

REVISIONS			
ECN NO.	DATE	DESCRIPTION	APPROVED
		PRODUCTION RELEASE	



NOTES

- MATERIALS:  
LEAD FRAME: COPPER 194FH, THK = 0.203±0.008  
BODY: SEMICONDUCTOR MOLDING EPOXY, CONTACT QUIK-PAK FOR DETAILS.
- FINISH:  
LEAD FRAME: ELECTROLESS NICKEL PER MIL-C-26074, CLASS 1, 100 TO 300 MICROINCHES (2.5um - 7.6um) THICK.  
GOLD PLATE PER MIL-G-45204, TYPE 3, GRADE A, CLASS 1 (40 TO 80 MICROINCHES (1um - 2um) THICK).  
BODY SURFACE FINISH: VDI 21-24 (1.12-1.6 Ra).
- PACKAGE MISMATCH: BODY OFFSET TO LEAD FRAME = 0.076mm MAX
- UNLESS OTHERWISE SPECIFIED, RADIUS ON ALL MOLDED EDGES AND CORNERS = 0.25mm MAX.
- PACKAGE CONFORMS TO JEDEC MO-220.



<p>THIRD ANGLE PROJECTION</p>	<p>DRAWN BY CAD DEPT. DATE 3/31/10</p>
	<p>APP BY STEVE S. DATE 3/31/10</p>
<p>UNLESS OTHERWISE SPECIFIED DIMENSIONS ARE IN MILLIMETER TOLERANCES ARE: X.XX ± 0.15 X.XXXX ± --- X.XXX ± 0.050 ANGLES: ± 1°</p>	<p>CUSTOMER ---</p>
<p>DO NOT SCALE DRAWING</p>	<p>THIS DOCUMENT CONTAINS INFORMATION PROPRIETARY TO QPTECHNOLOGIES, AND REPRODUCTION IN ANY FORM IS NOT PERMITTED WITHOUT WRITTEN AUTHORIZATION FROM QPTECHNOLOGIES.</p>



3mm X 3mm  
QFN 12 LEAD 0mPP

SIZE A	PART NO. QP-QFN12-3MM-.65MM	REV A1
SCALE NONE	CAD FILE	SHEET 1 OF 1

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